

Supporting Information

An ultra-low hysteresis, self-healing and stretchable conductor based on dynamic disulfide covalent adaptable networks

*Weibo Kong,^a Yunyun Yang,^{a,c} Yanjun Wang,^a Hongfei Cheng,^d Peiyao Yan,^a Lei Huang,^a Jingyi Ning,^a Fanhao Zeng,^a Xufu Cai,^{*a} and Ming Wang^{*b}*

I: Supplementary Tables and Captions

Table S1 Comparison of the state-of-the-art stretchable self-healing conductors

Matrix	Conductive materials	DH (%)	Stretchability (%)	Heal efficiency	Dynamic bonds	Heal temperature	Heal time
PDMS ¹	AgNWs	12	100	N/A	/	/	/
PDMS ²	Liquid metal	0.075	100	N/A	/	/	/
Ecoflex ³	Carbon black	2.41	200	N/A	/	/	/
PU ⁴	Graphene	7.03	100	N/A	/	/	/
PU ⁵	Liquid metal	52.84	500	78%	Hydrogen bonds	60°C	1.5 H
PU ⁶	Au	49.71	200	100%	Quadrupolar hydrogen bonds	RT	48 H
PU ⁷	AgNP layer	40.19	100	95%	Metal coordination bonds	70°C	48 H
PU ⁸	Au	62.04	1130	90%	Hydrogen bonds and coordination bonds	RT	48 H
PNIPAM ⁹	Graphene	22.78	300	96%	Hydrogen bonds	RT	2 H
Hydrogel ¹⁰	Ionic	25.88	1000	90%	Hydrogen bonds	RT	80 Min
PAA ¹¹	GO/Ca ²⁺	33.54	800	88.%	Hydrogen bonds and coordination bonds	RT	20 H
ENR ¹²	CNT layer	41.32	100	91%	Boroxine	RT	/
ENR ¹³	CNT	70.41	100	93%	Hydrogen bonds	RT	/
PU (this work)	Au	3.8	100	100%	Hydrogen bonds and disulfide bonds	130°C	1H

PDMS : polydimethylsiloxane ; PU: polyurethane; ENR: epoxidized natural rubber;

PNIPAM: polyisopropylacrylamide; PAA: polyacrylic acid;

Table S2 The chemical composition of PUs

Sample	IPDI(g)	PTMG1000(g)	TEA(g)	HEDS(g)	HDO(g)
PU-0	6.23	10	0	1.5425	0.9453
PU-1	5.35	10	0.3978	1.5425	0
PU-2	6.23	10	0.7957	1.5425	0
PU-3	8.90	10	1.9892	1.5425	0
Control	6.23	10	0.7957	0	1.182

II: Supplementary Figures and Captions

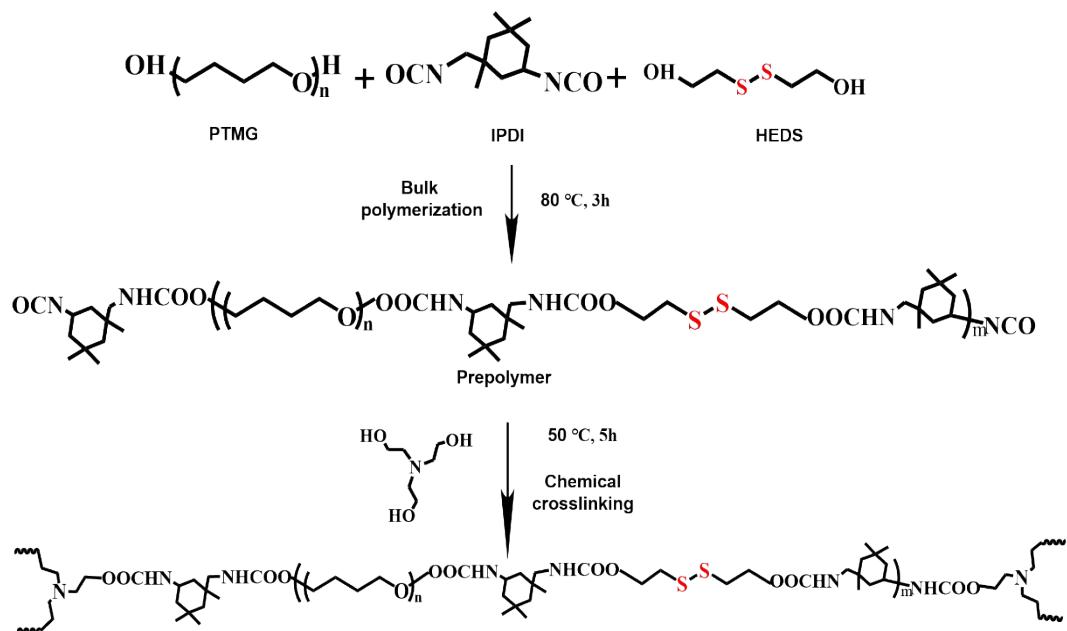


Fig. S1 The detailed synthetic route of PUs.



Fig. S2 The photograph of PU-2.

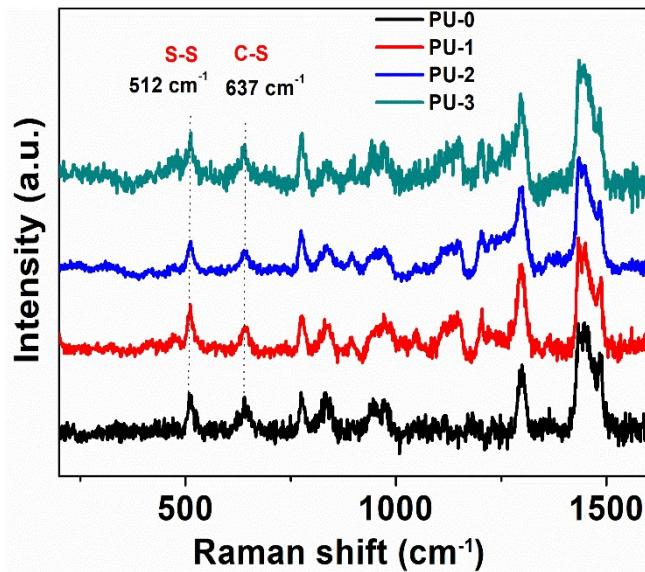


Fig. S3 Raman shift of the PU-0, PU-1, PU-2 and PU-3 samples with different weight ratios (0%, 2.30%, 4.29%, and 8.88%) of TEA crosslinkers.

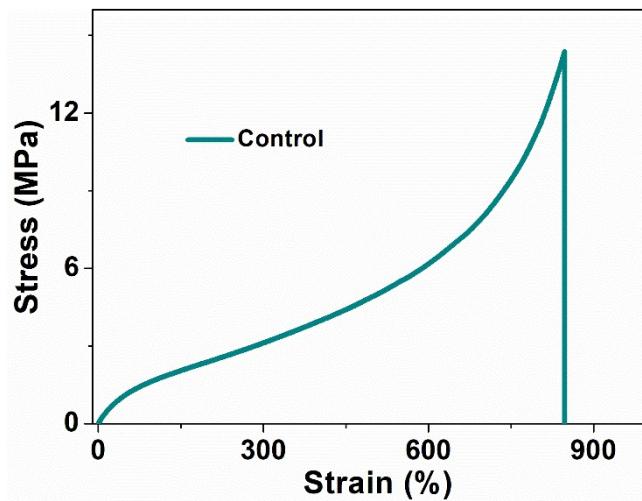


Fig. S4 The stress-strain curve of control sample under the stretching rate of 40 mm/min at room temperature.

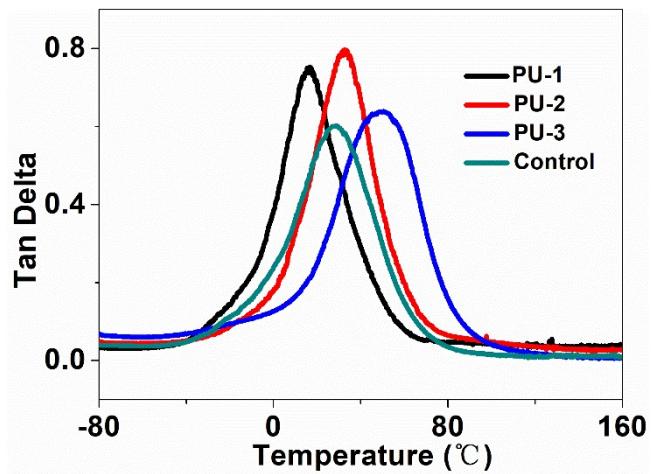


Fig. S5 Tan delta of PUs and control sample detected by DMA multiple strain model under heating rate of 5 °C/ min in temperature range of -80 °C ~ 160 °C.

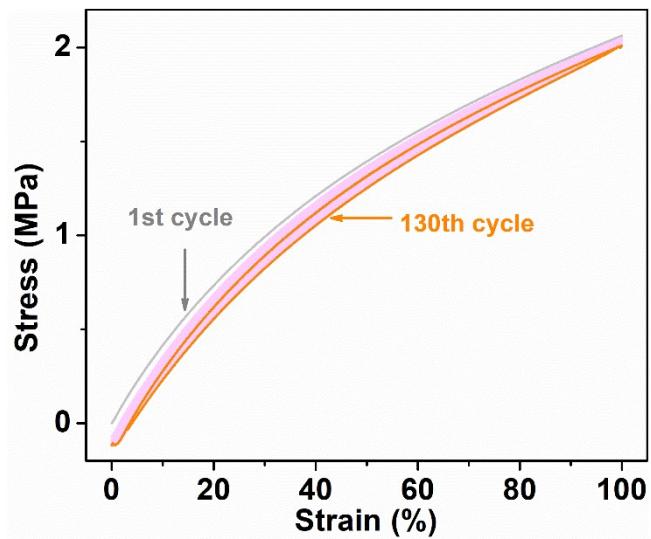


Fig. S6 Cyclic test of PU-2 at strain of 100% for 130 times.

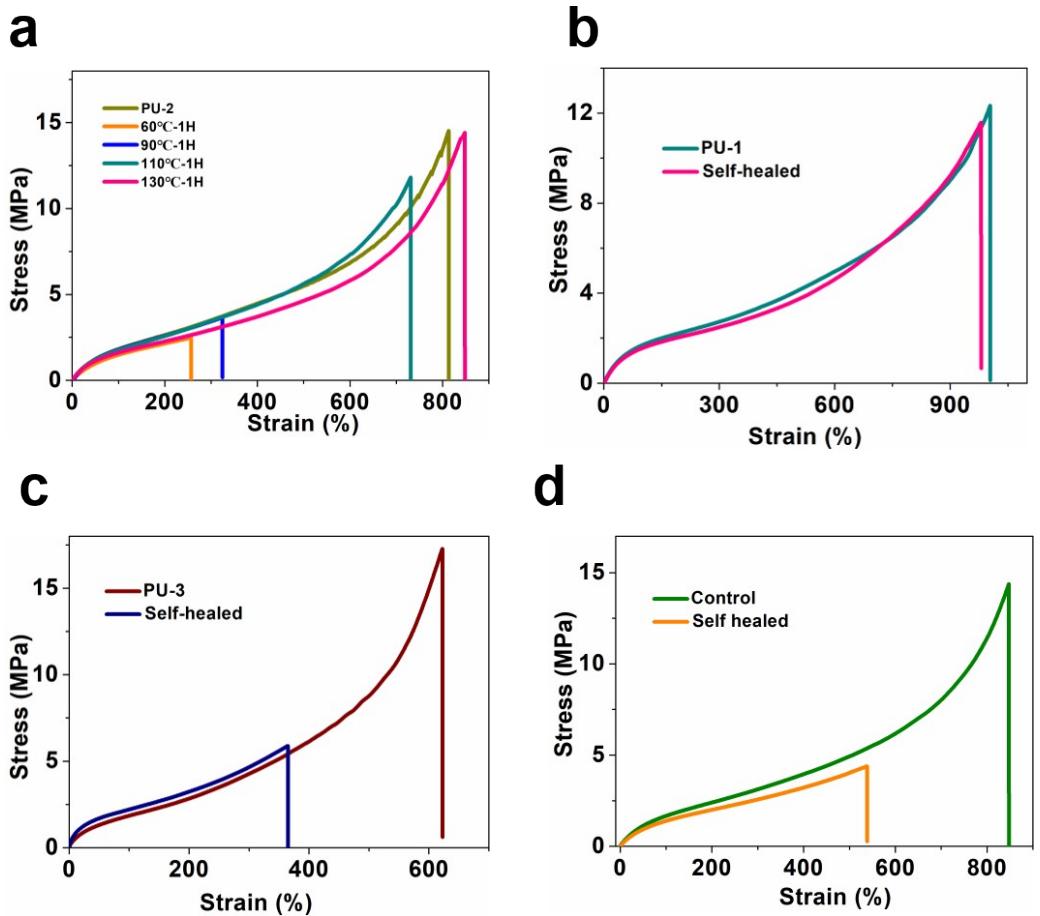


Fig. S7 (a) Stress-strain curves of the healed PU-2 at different temperature. (b)-(c) Stress-strain curves of original and self-healed PU-1 (b), PU-3 (c) and control (d) samples.

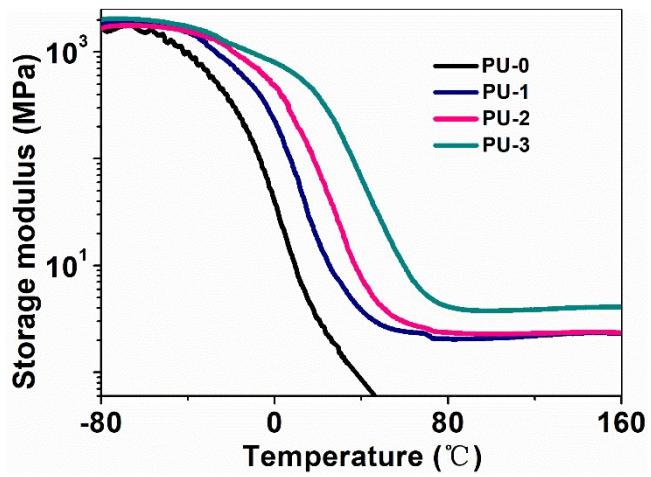


Fig. S8 Storage modulus of the PUs in the temperature range of -80 $^{\circ}\text{C}$ ~ 160 $^{\circ}\text{C}$ at a heating rate of 5 $^{\circ}\text{C}/\text{min}$ under 1 Hz.

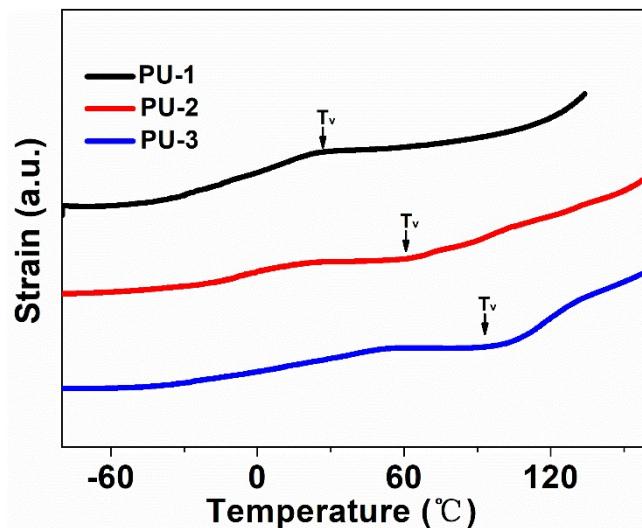


Fig. S9 Dilatometry tests of PUs under the DMA controlled force model under 0.1 MPa.

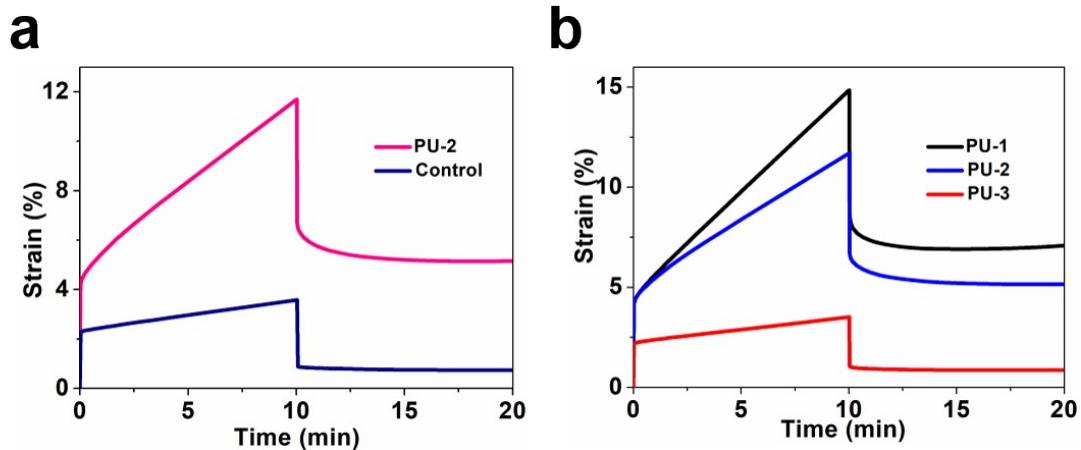


Fig. S10 reep curves of control sample (a) and PUs samples (b) at 150 °C.

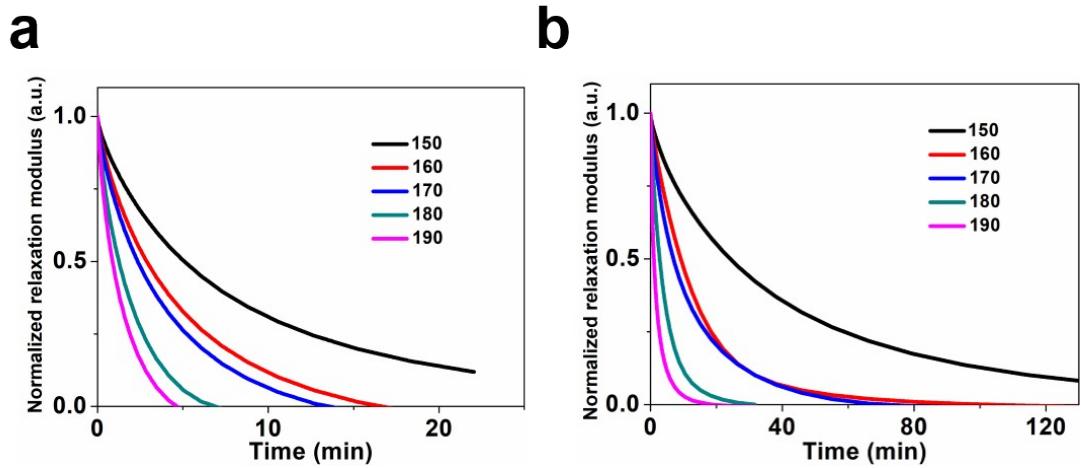


Fig. S11 Normalized stress relaxation curves of PU-1 (a) and PU-3 (b) under 5% of strain at different temperature.

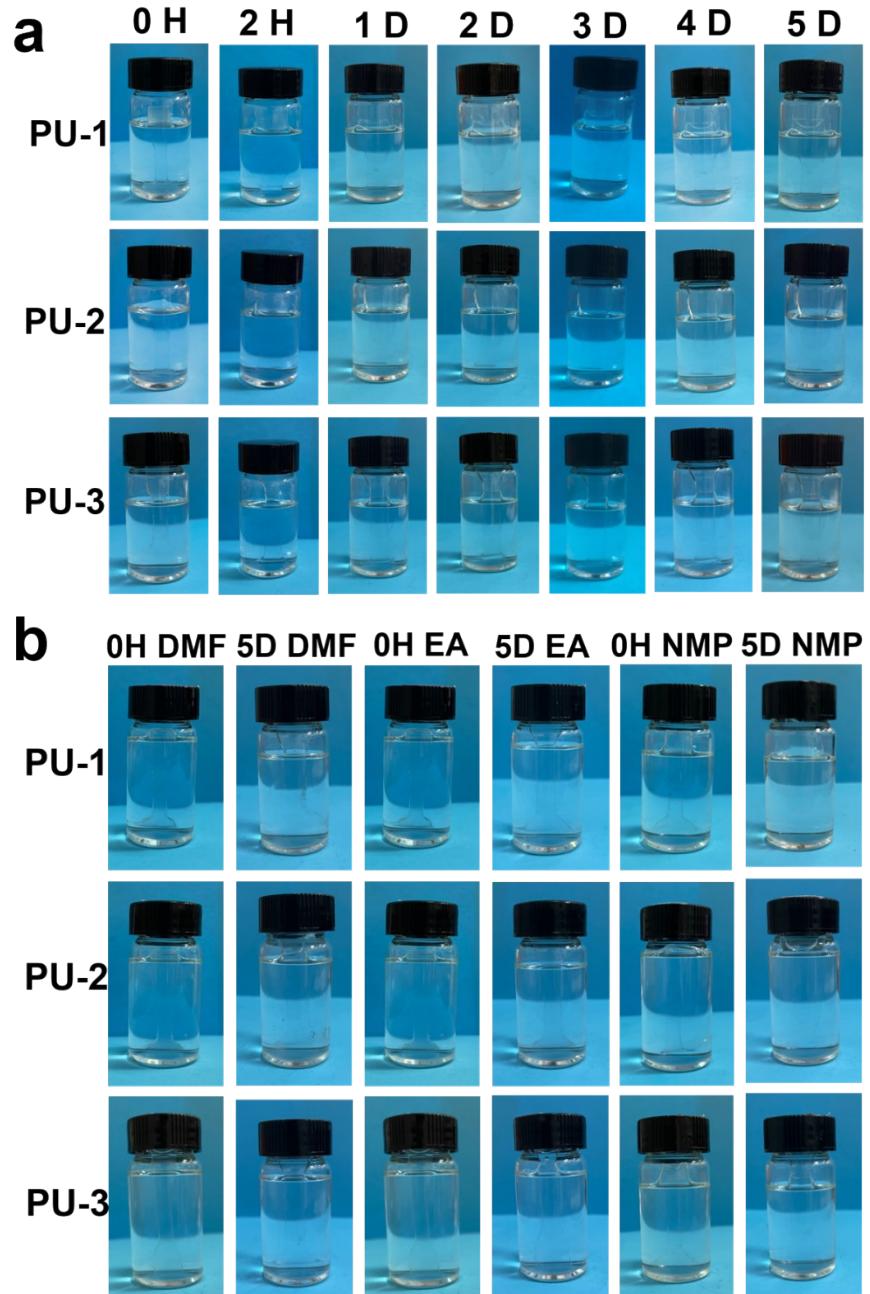


Fig. S12 (a) The photographs of PU-1, PU-2 and PU-3 in THF for different time. (b) The photographs of PU-1, PU-2 and PU-3 in DMF, EA and NMP for 5days.

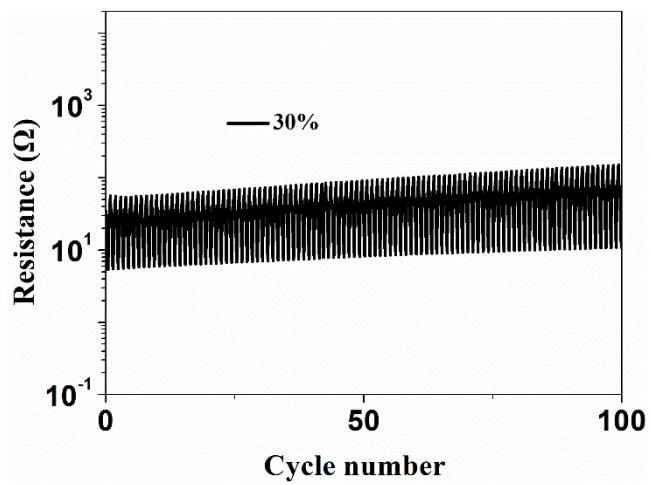


Fig. S13 Durability tests of 100 cycles at a maximum tensile strain of 30% for PU-2-based stretchable conductors.

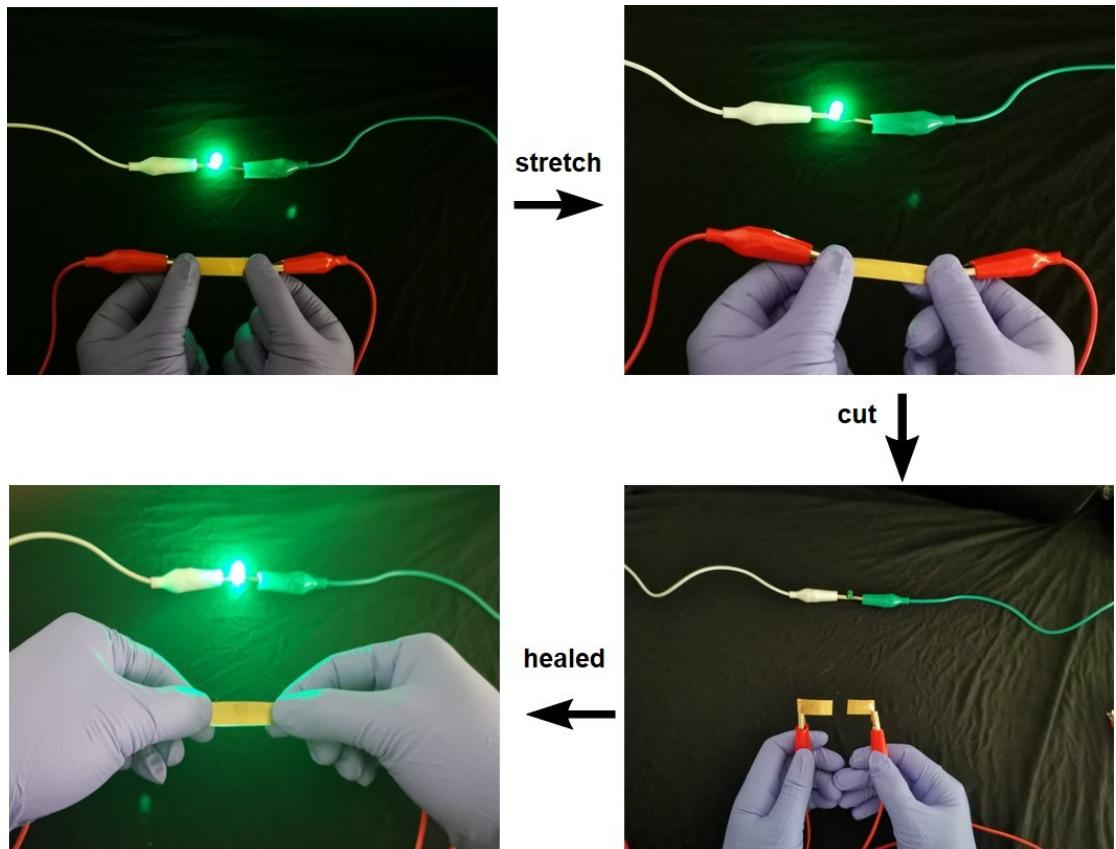


Fig. S14 Demonstration of the self-healing process of fabricated conductor connect with LED.

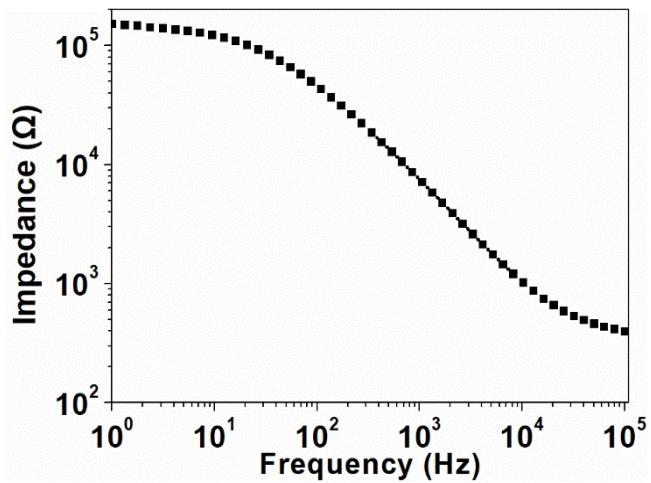


Fig. S15 The fabricated stretchable conductor showing low interfacial impedance with skin.

References:

- [1] H. Kim, A. Thukral, C. Yu, *ACS Appl. Mater. Inter.*, 2018, **10**, 5000.
- [2] Y. Wu, Y. Zhou, W. Asghar, Y. Liu, F. Li, D. Sun, C. Hu, Z. Wu, J. Shang, Z. Yu, R. Li, H. Yang, *Adv. Intell. Syst.*, 2021, 2000235.
- [3] P. Lugoda, J. C. Costa, L. A. Garcia Garcia, A. Pouryazdan, Z. Jocys, F. Spina, J. Salvage, D. Roggen, N. Münzenrieder, *Adv. Mat. Technol.*, 2021, **6**, 2000780.
- [4] X. Li, T. Hua, B. Xu, *Carbon.*, 2017, **118**, 686.
- [5] J. Kang, D. Son, G. J. N. Wang, Y. Liu, J. Lopez, Y. Kim, J. Y. Oh, T. Katsumata, J. Mun, Y. Lee, L. Jin, J. B. H. Tok, Z. Bao, *Adv. Mater.*, 2018, **30**, 1706846.
- [6] X. Yan, Z. Liu, Q. Zhang, J. Lopez, H. Wang, H. Wu, S. Niu, H. Yan, S. Wang, T. Lei, J. Li, D. Qi, P. Huang, J. Huang, Y. Zhang, Y. Wang, G. Li, J. B. H. Tok, X. Chen, Z. Bao, *J. Am. Chem. Soc.*, 2018, **140**, 5280.
- [7] J. Fan, J. Huang, Z. Gong, L. Cao, Y. Chen, *ACS Appl. Mater. Inter.*, 2021, **13**, 1135.
- [8] X. Wu, J. Wang, J. Huang, S. Yang, *ACS Appl. Mater. Inter.*, 2019, **11**, 7387.
- [9] S. Yan, G. Zhang, H. Jiang, F. Li, L. Zhang, Y. Xia, Z. Wang, Y. Wu, H. Li, *ACS Appl. Mater. Inter.*, 2019, **11**, 10736.
- [10] H. Qiao, P. Qi, X. Zhang, L. Wang, Y. Tan, Z. Luan, Y. Xia, Y. Li, K. Sui, *ACS Appl. Mater. Inter.*, 2019, **11**, 7755.
- [11] Y. Wang, Q. Chang, R. Zhan, *J. Mater. Chem. A*, 2019, **7**, 24814-24829.
- [12] Q. Guo, B. Huang, C. Lu, T. Zhou, G. Su, L. Jia, X. Zhang, *Mater. Horizons.*, 2019, **6**, 996.
- [13] J. Cao, C. Lu, J. Zhuang, M. Liu, X. Zhang, Y. Yu, Q. Tao, *Angew. Chem. Int. Ed.*, 2017, **56**, 8795.